PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Release of Patent Pledge Agreement

CONVEYING PARTY DATA

Name	Execution Date
ASML Netherlands B.V.	07/07/2009

RECEIVING PARTY DATA

Name:	Micronic Laser Systems AB (PUBL)
Street Address:	Nytorpsvagen 9
City:	Taby
State/Country:	SWEDEN
Postal Code:	183 03

PROPERTY NUMBERS Total: 52

Property Type	Number
Application Number:	09623200
Application Number:	09623270
Application Number:	09623308
Application Number:	09623195
Application Number:	09623310
Application Number:	09623311
Application Number:	09623194
Application Number:	10049286
Application Number:	09954721
Application Number:	60528488
Application Number:	60529114
Application Number:	60537887
Application Number:	09869922
Application Number:	10129364
Application Number:	10953560

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Application Number:	10130070
Application Number:	09664288
Application Number:	10704957
Application Number:	09824670
Application Number:	10238177
Application Number:	10238220
Application Number:	10488353
Application Number:	09992653
Application Number:	09995526
Application Number:	10657526
Application Number:	10308917
Application Number:	10310637
Application Number:	10498590
Application Number:	10498713
Application Number:	10505564
Application Number:	10507554
Application Number:	10510059
Application Number:	10410874
Application Number:	10462010
Application Number:	10460765
Application Number:	10449661
Application Number:	10911412
Application Number:	10634152
Application Number:	10911218
Application Number:	10987589
Application Number:	11008566
Application Number:	60535106
Application Number:	10776192
Application Number:	10782863
Application Number:	60547614
Application Number:	60552598
Application Number:	10827530
Application Number:	60603275
Application Number:	10937737
Application Number:	60610012

Application Number:	60615788
Application Number:	60623928

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	0107945.00174
NAME OF SUBMITTER:	Kathleen M. Bastarache

Total Attachments: 6
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RELEASE OF PATENT PLEDGE AGREEMENT COVERING INTERESTS IN PATENTS

Reference is made to the Patent Pledge Agreement, dated December 10, 2004, (the "Agreement") between **Micronic Laser Systems AB (PUBL)**, a limited liability company incorporated in Sweden under registration number 556351-2374, whose registered office is at Nytorpsvägen 9, 183 03 Täby, Sweden ("Micronic"), and **ASML Netherlands B.V.**, a company incorporated under the laws of the Netherlands, whose registered office is at De Run 6501, 5504 DR Veldhoven, the Netherlands, ("ASML"). As of **April 30, 2009**, ASML releases and terminates its pledge and security interest in the Security Assets (as defined in the Patent Pledge Agreement) set forth in the **Sub-Schedule 2.1** attached hereto.

Dated: July 7, 2009

ASML Netherlands B.V. by
C. Hall Swaim, Esq., its duly authorized attorney

Wilmer Cutler Pickering Hale & Dorr LLP.
60 State Street
Boston, Massachusetts 02109
T: 617.526.6716

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This Patent Pledge Agreement (the "Pledge Agreement") is dated ___ December 2004 (the "Date of this Agreement") and made between:

(1) MICRONIC LASER SYSTEMS AB (PUBL), a limited liability company incorporated in Sweden under registration number 556351-2374, whose registered office is at Nytorpsvägen 9, 183 03 Täby, Sweden, (the "Pledgor"); and

(2) ASML NETHERLANDS B.V., a company incorporated under the laws of the Netherlands, whose registered office is at De Run 6501, 5504 DR Veldhoven, the Netherlands, (the "Pledgee").

Background

(A) The Pledgor and the Pledgee have on the Date of this Agreement entered into a license agreement, (the "License Agreement") regarding certain patents and other intellectual property rights.

(B) The parties have entered into this Pledge Agreement for the purpose of the Pledgor providing certain security to the Pledgee in relation to the obligations of the Pledgor to repay the Deposit or part thereof pursuant to the License Agreement.

It is agreed as follows:

1 Definitions

Unless otherwise evident from this Pledge Agreement, terms used in the License Agreement shall have the same meaning and construction in this Pledge Agreement. In addition, the below definitions are used in this Pledge Agreement:

"Encumbrance" means any mortgage, pledge, lien, charge or other security interest or any other agreement or arrangement having the commercial effect of conferring security, with the exception of the floating charges set forth in the enclosed extract from the Swedish Floating Charge Register (Sw. *Företagsinteckningsregistret*), Schedule 1.

"Enforcement Event" has the meaning given to it in Section 6.

"Liabilities" means the obligation of the Pledgor to repay the Deposit, or part thereof, and any interest accrued thereupon, to the Pledgee according to the License Agreement, with the exclusion of Section 7.2 (a) in case the Pledgor has challenged that it is under the obligation to repay the Deposit, or part thereof, on the ground that ASML has not met the requirement for such repayment as per Section 7.2 (a).

Negative Pledge Obligation means the Pledgor's negative pledge undertakings given to FöreningsSparbanken AB (publ) and Danske Bank.

"Patents" means the patents and patent applications set out in Schedule 2 (*Patents*);

"Pledge" means the first priority pledge over the Security Assets created or expressed to be created by or pursuant to this Pledge Agreement;

"Proceeds" means the proceeds from the realisation of the Security Assets, together with any monies received by the Pledgee in respect of the Security Assets, after deduction of all costs and expenses incurred by the Pledgee in connection with the enforcement of this Pledge Agreement and the realisation of the Security Assets; and

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"Security Assets" means all of the Pledgor's rights to and interests in those of the patents that have been listed in the notice to be delivered by the Pledgee to the Pledgor pursuant to Clause 2.2.2 below.

2 Security

2.1 Pledge of Security Assets

The Pledgor hereby irrevocably and unconditionally, on the terms and conditions set out herein, pledges to the Pledgee, and thereby creates a first priority right of pledge in favour of the Pledgee in respect of, the Security Assets for the purpose of constituting security for the due and punctual payment, discharge and performance, as the case may be, of the Liabilities.

2.2 Perfection

2.2.1 The Pledgor hereby authorises the Pledgee to take necessary actions to duly perfect the Pledge created hereunder in accordance with the relevant requirements in the applicable jurisdictions set out in Schedule 1 and the Pledgor shall promptly execute, acknowledge and deliver all such further documents, power of attorney, instruments, notifications and confirmations as may be required for the Pledgee to be able to perfect the Pledge. If the perfection should require the entering into a separate pledge agreement, or require that the Pledgor take certain actions which cannot be performed by the Pledgee in order to perfect the Pledge, the Parties undertake to enter into such agreement on terms and conditions corresponding to this Pledge Agreement, and the Pledgor undertakes to take such necessary actions.

2.2.2 The Pledgee shall within two (2) months as from the Date of this Agreement (or such later date which may apply pursuant to second paragraph of Clause 2.2.3 below) notify the Pledgor as to which of the Patents and jurisdictions the Pledgee requires that the Pledge shall be perfected. Such notice shall contain those of the Patents regarding which the Pledgee intends to complete the perfection of the Pledge. Once such notice has been given, those of the Patents that the Pledgee has decided not to be perfected shall not be part of the Security Assets.

2.2.3 The Pledgor undertakes to provide the Pledgee with a complete and accurate table containing the below details of the Patents:

(i) identification of patent families;

(ii) under each patent family, identification by name and number of each national patent or pending application within such family;

(iii) registered owner of the patents and pending applications;

(iv) details of status of the patents and pending applications; and,

(v) as regards EPC and PCT applications, information as to designated countries or, if applicable, countries in which the application is being pursued.

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15.2 Dispute Resolution

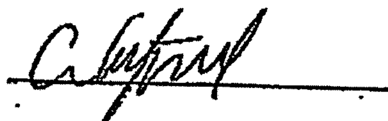
Any dispute, controversy or claim arising out of or in connection with this Pledge Agreement, or breach, termination or invalidity thereof, shall be finally settled by arbitration in accordance with the Rules of the Arbitration Institute of the Stockholm Chamber of Commerce. The tribunal shall be composed of three arbitrators. The place of arbitration shall be Stockholm. The language to be used in the arbitral proceeding shall be English.

This Pledge Agreement has been executed in two originals, of which the Parties hereto have received one each.

Stockholm, Sweden

10 December 2004

MICRONIC LASER SYSTEMS AB (PUBL)



Sven Löfquist

Clarification of signature

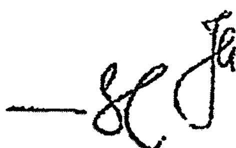
Veldhoven, The Netherlands

10 December 2004

ASML NETHERLANDS B.V.

PETER WENNINK

Clarification of signature



Sub-Sct ıle 2.1 (U.S. Filings Only)

Micronic

reference	Country	Date Filed	App. No.	Reg. Date	Reg. No.	Status	TitleMark
P00010b	USA	3/2/99	09/623,200	6/4/02	6,399,261	Reg.	Pattern generator with improved precision
P00010d	USA	3/2/99	09/623,270	2/13/04	6,687,041	Reg.	Pattern generator using euv
P00010f	USA	3/2/99	09/623,308	4/16/02	6,373,619	Reg.	Pattern generator with improved address resolution
P00010a	USA	3/2/99	09/623,195	6/8/04	6,747,783	Reg.	Improved pattern generator
P00010c	USA	3/2/99	09/623,310	9/4/01	6,285,488	Reg.	Improved pattern generator for avoiding stitching errors
P00010g	USA	3/2/99	09/623,311	1/7/03	6,504,644	Reg.	Improved modulator design for pattern generator
P00010e	USA	3/2/99	09/623 194	8/6/02	6,428,940	Reg.	Method for pattern generation with improved image quality
P00015	USA	9/8/00	10/049,286	4/6/04	6,717,097	Reg.	Data Path for high Performance pattern generator
P00125	USA	9/12/01	09/954,721			Pend.	Graphics Engine for High Precision Lithography
P00198	USA	12/11/03	60/528,488			Pend.	Phase step mirror
P00198	USA	12/15/03	60/529,114			Pend.	Phase step mirror
P00198	USA	1/22/04	60/537,887			Pend.	Phase step mirror
P00013	USA	1/21/00	09/869,922	9/23/03	6624878	Reg.	Laser Writer
P00017	USA	11/24/00	10/129,364	11/2/04	6,813,058	Reg.	Method and apparatus for personalization of semiconductor
P00017-2	USA	9/30/04	10/953,560			Pend.	Method and apparatus for personalization of semiconductor
P00018	USA	4/10/01	10/130 070	3/2/04	6,700,095	Reg.	Pattern generation system using a spatial light modulator
P00020	USA	9/18/00	09/664,288	11/11/03	6,645,677	Reg.	Dual layer reticle blank and manufacturing process
P00020-2	USA	11/10/03	10/704,957			Pend.	Dual layer reticle blank and manufacturing process
P00104	USA	4/4/01	09/824,670	11/9/04	6,816,302	Reg.	Pattern Generator
P00117	USA	9/10/02	10/238,177	11/16/04	6,819,490	Reg.	Homogenization of a spatially coherent radiation beam & printing & inspection, respectively, of a pattern on a workpiece
P00107	USA	9/10/02	10/238,220			Pend.	Method and apparatus using an SLM
P00127	USA	9/16/01	10/488,353			Pend.	Bonding method
P00132	USA	11/16/01	09/992,653	8/12/03	6,605,816	Reg.	Reticle and direct lithography writing strategy
P00108	USA	11/28/01	09/995,526	9/9/03	6,618,185	Reg.	Defective pixel compensating method
P00108	USA	9/8/03	10/657,526	11/2/04	6,813,062	Reg.	Defective pixel compensating method
P00138	USA	12/3/02	10/308,917			Pend.	Homogenizer
P00139	USA	12/4/02	10/310,637			Pend.	Alignment sensor
P00120	USA	12/10/02	10/498,590			Pend.	Method and apparatus for image formation
P00116	USA	12/11/02	10/498,713			Pend.	Method and apparatus for patterning a workpiece
P00118	USA	2/13/03	10/505,564			Pend.	An image forming method and apparatus
P00140	USA	3/14/03	10/507,554			Pend.	Improved addressing method
P00135	USA	4/1/03	10/510,059			Pend.	A mask blank and a method for producing the same
P00175-1	USA	4/10/03	10/410,874			Pend.	Methods and systems for process control of corner feature embellishment
P00175-2	USA	6/12/03	10/462,010			Pend.	Negative Black

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reference	Country	Date Filed	App. No.	Reg. Date	Reg. No.	Status	TitleMark
P00187	USA	6/12/03	10/460,765	12/21/04	6,833,854	Reg.	Method for precision printing of patterns
P00188	USA	5/30/03	10/449,661			Pend.	Improved pattern generator mirror configuration
P00168	USA	8/4/04	10/911,412			Pend.	Method to pattern a substrate
P00168	USA	8/4/03	10/634,152			Pend.	Method to pattern a substrate
P00183	USA	8/4/04	10/911,218			Pend.	Enhancement of SLM lithographic systems
P00108-2	USA	9/8/03	10/657,526	11/2/04	6,813,062	Reg.	Defective pixel compensating method
P00194	USA	11/12/04	10/987,589			Pend.	Method & device for correcting SLM stamp image imperfections
P00198	USA	12/10/04	11/008,566			Pend.	Method and apparatus for patterning a workpiece and methods of manufacturing the same
P00199	USA	1/8/04	60/535,106			Pend.	Data Integrity
P00010a	USA	2/12/04	10/776,192			Pend.	Improved pattern generator
P00015-2	USA	2/24/04	10/782,863			Pend.	Data Path for high Performance pattern generator
P00207	USA	2/25/04	60/547,614			Pend.	RET for optical maskless lithography
P00207	USA	3/12/04	60/552,598			Pend.	RET for optical maskless lithography
P00211	USA	4/20/04	10/827,530			Pend.	A method for error reduction in Lithography
P00217	USA	8/23/04	60/603,275			Pend.	Pupil optimization of incoherent imaging systems for improved CD linearity
P00204	USA	9/9/04	10/937,737			Pend.	Healing algorithm
P00218	USA	9/15/04	60/610,012			Pend.	Phase shifting optical maskless lithography enabling ASICs at the 65 and 45 nm nodes
P00218	USA	10/4/04	60/615,788			Pend.	Phase shifting optical maskless lithography enabling ASICs at the 65 and 45 nm nodes
P00178	USA	11/1/04	60/623,928			Pend.	Calibration

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